PCB LOGO
Texas Instruments

Label Table

<table>
<thead>
<tr>
<th>Variant</th>
<th>Label Text</th>
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</thead>
<tbody>
<tr>
<td>001</td>
<td>ChangeMe!</td>
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<tr>
<td>002</td>
<td>ChangeMe!</td>
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</tbody>
</table>

Assembly Note

.instance ZZ1 This Assembly Note is for PCB labels only.

.instance ZZ2 These assemblies are ESD sensitive, ESD precautions shall be observed.

.instance ZZ3 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

.instance ZZ4 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
Vin = 8V to 20V DC

All of the power ground connections should be connected to a single point. Also, all of the noise sensitive low power ground connections should be connected together near the AGND pin and a single sensitive low power ground should be connected to a single point. Also, all of the noise sensitive low power ground connections should be connected together near the AGND pin and a single sensitive low power ground should be connected to a single point. Please note that the design will meet the specifications, will be suitable for your application, or for any particular purpose, or will operate in an environment. Texas Instruments and its licensor do not warrant that the design is production worthy. You should completely validate and test your design implementation to confirm the system functionality for your application.
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It has a Power PAD on Top of the IC and need to be connected to Heat Sink ATS-T1 10.

OP-521-C1-R1.
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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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